

## DAFTAR PUSTAKA

1. Wahyudi, E., & Lestari, S. (2020). *Perancangan Alat Electroplating Otomatis Berbasis Mikrokontroler*. Jurnal Teknik Mesin, 12(1), 34–40.
2. Prabowo, H., & Santosa, S. (2019). *Pengaruh Tegangan dan Waktu Terhadap Ketebalan Lapisan Tembaga pada Proses Electroplating*. Jurnal Metalurgi dan Material, 23(2), 75–82.
3. Fitriani, D., & Ramadhan, T. (2021). *Analisis Efisiensi Proses Electroplating Menggunakan Larutan  $CuSO_4$  dan  $H_2SO_4$* . Jurnal Sains Terapan Elektro, 9(1), 12–18.
4. Nugroho, A., & Susanto, R. (2022). *Penggunaan PTC Heater dalam Pengaturan Suhu Larutan Electroplating Skala Laboratorium*. Jurnal Inovasi Teknologi, 5(3), 45–50.
5. Kurniawan, A., & Hadi, M. (2020). *Rancang Bangun Sistem Timer Digital untuk Proses Electroplating Otomatis*. Jurnal Rekayasa Elektronika dan Instrumentasi, 14(2), 89–95.
6. Harris, D. C. (2010). *Quantitative Chemical Analysis* (8th ed.). W. H. Freeman and Company.
7. Skoog, D. A., Holler, F. J., & Crouch, S. R. (2013). *Principles of Instrumental Analysis* (6th ed.). Cengage Learning.
8. *Design and Fabrication of Electroplating Equipment Using Copper Anode*" oleh Ananda et al. (2020),
9. *"Analysis of Copper Coating by Electroplating Process with Variable Current and Time"* oleh Patel & Mehta (2019),
10. *IEEE Transactions on Applied Electrochemistry* (2018).
11. *Design of Copper Electroplating System with Variable Time and Current Settings* (Ananda et al., 2020)
12. *Analysis of Copper Electroplating on Mild Steel Using Acidic Bath and Low Voltage Parameters* (Irfan et al., 2021)
13. *Optimization of Parameters in Electroplating for Uniform Copper Coating* (Patel & Mehta, 2019)